

In the Claims:

Please cancel claims 1-5, 8-10, 12-14, 20, 25-36, and 38-41.

Please amend the claims to appear as follows:

Sub C1 15. A method of mounting an electrical connector to a substrate, comprising:
providing an electrical connector having a contact and a hold down;
providing a substrate having a pad;
securing said contact to said pad on said substrate during a reflow process;
placing said hold down into a hole in said substrate so as to permit said
contact to center on said pad upon mounting to the substrate without contacting another pad on
the substrate, wherein said hold down is adapted to retain said housing a distance from a surface
of the substrate; and
securing said hold down to said substrate during said reflow process
subsequent to said securing of said contact, wherein said hold down is adapted to limit flattening
of said contact during said reflow process.

Please add claims 42-46, as follows:

Sub 42 A connector/substrate combination manufactured by the following steps:
providing an electrical connector having a contact and a hold down;
providing a substrate having a pad;
securing said contact to said pad on said substrate during a reflow process;
placing said hold down into a hole in said substrate so as to permit said
contact to center on said pad upon mounting to the substrate without contacting another pad on
the substrate, wherein said hold down is adapted to retain said housing a distance from a surface
of the substrate; and

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10 securing said hold down to said substrate during said reflow process
11 subsequent to said securing of said contact, wherein said hold down is adapted to limit flattening
12 of said contact during said reflow process.

43. The connector/substrate combination as recited in claim 42, wherein said step of securing comprises soldering said hold down to said substrate.

D2 44. The connector/substrate combination as recited in claim 42, further comprising the step of constructing said electrical connector such that it remains substantially parallel when mounted to said substrate.

45. The connector/substrate combination as recited in claim 42, further comprising the step of balancing said electrical connector on said substrate such that said electrical connector remains substantially parallel to said substrate during said securing.

46. The connector/substrate combination as recited in claim 42, wherein said connector is a ball grid array connector.
